

IN THE SPECIFICATION:

Please rewrite the "Brief Description of the Drawings" section, on pages 5 and 6 of the substitute specification, as shown below:

BRIEF DESCRIPTION OF THE DRAWINGS

~~Fig. 1 is a view~~ Figs. 1A-1C are views showing the steps of fabricating in a first embodiment of a method of fabricating a semiconductor package according to the invention;

Fig. 2 is a partly sectional view of the semiconductor package obtained by the first embodiment of the method of fabricating the semiconductor package;

~~Fig. 3 is a view~~ Figs. 3A-3C are views showing the steps of fabricating in a second embodiment of a method of fabricating a semiconductor package according to the invention;

Fig. 4 is a partly sectional view of the semiconductor package obtained by the second embodiment of the method of fabricating the semiconductor package;

Fig. 5 is a partly enlarged sectional view of a third embodiment of a method of fabricating a semiconductor package according to the invention, showing a part of a lead frame;

~~Fig. 6 is a view~~ Figs. 6A-6C are views showing the steps of fabricating in a fourth embodiment of a method of fabricating a semiconductor package according to the invention; and

~~Fig. 7 is a view~~ Figs. 7A-7C are views showing the steps of fabricating in a fifth embodiment of a method of fabricating a semiconductor package according to the invention.